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PATENT

**FIELD EFFECT TRANSISTOR STRUCTURE WITH SELF-ALIGNED RAISED
SOURCE/DRAIN EXTENSIONS**

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Background of the Invention

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Field of the Invention

The invention relates to metal-oxide-semiconductor field effect transistors (MOSFETs) and more particularly to transistor structures having self-aligned raised source/drain regions, and methods of making same.

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Background

The trend of integrating more functions on a single substrate while operating at ever higher frequencies has existed in the semiconductor industry for many years. Advances in both semiconductor process technology and digital system architecture have aided in producing these more highly integrated and faster operating integrated circuits.

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The desired result of many recent advances in semiconductor process technology has been to reduce the dimensions of the transistors used to form the individual circuits found on integrated circuits. There are several well-recognized benefits of reducing the size of transistors. In the case of MOSFETs, reducing the channel length provides the capability to deliver a given amount of drive current with a smaller channel width. By reducing the width and length of a FET, the parasitic gate capacitance, which is a function of the area defined by the width and length can be reduced, thereby improving circuit performance.

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Similarly, reducing the size of transistors is beneficial in that less area is consumed for a given circuit, and this allows more circuits in a given area, or a smaller, less costly chip, or both.

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It has also been well known that MOSFETs can not simply be scaled down linearly. That is, as the width and length attributes of a MOSFET are reduced, other parts of the transistor, such as the gate dielectric and the

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junctions must also be scaled so as to achieve the desired electrical characteristics. Undesirable electrical characteristics in MOSFETs due to improper scaling include coupling of the electric field into the channel region and increased subthreshold conduction. These effects are sometimes referred to in this field as short channel effects.

A number of methods have been developed to form ever more shallow source/drain junctions for MOSFETs in order to achieve proper scaling. Unfortunately, these very shallow junctions create source/drain extensions that have increased resistivity as compared with deeper source/drain junctions. In longer channel length MOSFETs with deeper source/drain junctions, the source/drain extension resistivity was negligible compared to the on-resistance of the MOSFET itself. However, as MOSFET channel lengths decrease into the deep sub-micron region, the increased source/drain extension resistivity becomes a significant performance limitation.

What is needed is a field effect transistor structure having very short channel length and low source/drain extension resistivity, yet operable to produce high drive currents without suffering from the short channel effects that produce significant levels of off-state current. What is further needed is a method of manufacturing such a structure.

Summary of the Invention

Briefly, field effect transistor structures include a channel regions formed in a recessed portion of a substrate. The recessed channel portion permits the use of relatively thicker source/drain regions thereby providing lower source/drain extension resistivity while maintaining the physical separation needed to overcome various short channel effects.

In a further aspect of the present invention, the surface of the recessed channel portion may be of a rectangular, polygonal, or curvilinear shape.

Brief Description of the Drawings

Fig. 1 is a schematic cross-section of a conventional MOSFET showing symmetrical source/drains with source/drain extensions.

Fig. 2 is a schematic cross-section of a MOSFET having raised source/drain extension in accordance with a first exemplary embodiment of the present invention

Fig. 3 is a schematic cross-section of a MOSFET in accordance with a second exemplary embodiment of the present invention having tapered edges and raised source/drain extensions.

Fig. 4 is a schematic cross-section of a MOSFET in accordance with a third exemplary embodiment of the present invention having a curvilinear gate dielectric and raised source/drain extensions.

Fig. 5 is a schematic cross-section of a wafer having an etch stop layer and an unpatterned damascene layer formed thereon.

Fig. 6 is a schematic cross-section showing the structure of Fig. 5, after the damascene and etch stop layers have been patterned.

Fig. 7 is a schematic cross-section showing the structure of Fig. 6, after a first spacer layer has been formed adjacent to the sidewalls of the patterned damascene and etch stop layers.

Fig. 8 is a schematic cross-section showing the structure of Fig. 7, after the exposed silicon has been anisotropically etched.

Fig. 9 is a schematic cross-section showing the structure of Fig. 8, after the second spacer has been removed, a gate oxide layer grown over the exposed silicon, and a gate electrode layer deposited over the wafer.

Fig. 10 is a schematic cross-section showing the structure of Fig. 9, after the gate electrode is formed by a chemical mechanical polishing operation which removes the excess gate electrode material.

Fig. 11 is a schematic cross-section showing the structure of Fig. 10, after the damascene, first spacer, and etch stop layers have been etched away.

Fig. 12 is a schematic cross-section showing a completed MOSFET formed from the structure of Fig. 11, after conventional processing operations
5 such as source/drain extension implants, gate spacer formation, deep source/drain implants, and silicidation of source/drains and gate electrode.

Fig. 13 is a schematic cross-section showing the structure of Fig. 7, after the exposed silicon has been oxidized, and the exposed oxidized silicon has been etched, forming a recess with tapered.

10 Fig. 14 is a schematic cross-section showing the structure of Fig. 13, after the second spacer has been removed, a gate oxide layer grown over the exposed silicon, and a gate electrode layer deposited over the wafer.

Fig. 15 is a schematic cross-section showing the structure of Fig. 14, after the gate electrode is formed by a chemical mechanical polishing operation which
15 removes the excess gate electrode material.

Fig. 16 is a schematic cross-section showing the structure of Fig. 15, after the damascene, first spacer, and etch stop layers have been etched away.

Fig. 17 is a schematic cross-section showing a completed MOSFET formed from the structure of Fig. 16, after conventional processing operations
20 such as source/drain extension implants, gate spacer formation, deep source/drain implants, and silicidation of source/drains and gate electrode.

Fig. 18 is a schematic cross-section showing the structure of Fig. 7, after the exposed silicon has been isotropically etched.

Fig. 19 is a schematic cross-section showing the structure of Fig. 18, after
25 the second spacer has been removed, a gate oxide layer grown over the exposed silicon, and a gate electrode layer deposited over the wafer.

Fig. 20 is a schematic cross-section showing the structure of Fig. 19, after the gate electrode is formed by a chemical mechanical polishing operation which removes the excess gate electrode material.

Fig. 21 is a schematic cross-section showing the structure of Fig. 20, after the damascene, first spacer, and etch stop layers have been etched away.

Fig. 22 is a schematic cross-section showing a completed MOSFET formed from the structure of Fig. 21, after conventional processing operations such as source/drain extension implants, gate spacer formation, deep source/drain implants, and silicidation of source/drains and gate electrode.

Fig. 23 is a flow diagram of a process in accordance with the present invention.

Detailed Description

Overview

In order to continue to scale the MOSFET to smaller dimensions, it is necessary to scale both the lateral dimensions (e.g., gate length) as well as the vertical dimensions (e.g., junction depth). In particular, it is required to reduce the depth of the source/drain extension (SDE) as the dimensions of the MOSFET are scaled down, so as to reduce short channel effects. However, as SDE depth is reduced, the electrical resistance of this region is increased, thereby reducing transistor performance. Additionally, transistor performance is adversely affected by the reduction of SDE depth because current through the transistor needs to spread out from the thin accumulation layer.

Simply increasing the SDE depth, that is, its thickness, addresses the series resistance problem at the expense of having to tolerate short channel effects that are adverse to increased transistor performance. Conventional transistor structure engineering has focused on optimizing the trade-off between SDE depth and transistor performance, rather than trying to re-engineer the relationship between the thickness of the SDE and role of SDE thickness in inducing undesired short channel effects in MOSFETs.

Elevating the SDE region that is outside gate control, using , for example, a selective epitaxy process, can reduce the series resistance to a limited extent. However, because the SDE region under the gate, which is where most of the current spreading takes place, is not affected, the benefit of elevating the SDE region outside of gate control is of limited value. The elevated (also referred to as raised) SDE typically creates additional undesired gate-to-drain and gate-to-source overlap capacitance.

MOSFETs in accordance with an exemplary embodiment of the present invention include self-aligned, elevated SDE regions. More particularly, as can be seen in Figs. 2-4, the SDE regions are elevated with respect to the channel region. Because the elevated SDE regions underlie the gate electrode they are affected by the electric field induced by the charge on the gate electrode. This gate control effectively reduces the series resistance in the SDE regions. The SDEs in MOSFETs that embody the present invention can have increased thickness, relative to conventional MOSFETs, to reduce series resistance because the portion of the SDE that protrudes below the recessed central channel region is shallow, and therefore short channel effects are reduced. Furthermore, because the elevated SDE in accordance with the present invention is self-aligned to the gate electrode, overlap capacitance is reduced relative to conventional raised SDE structures.

Terminology

The terms, chip, integrated circuit, monolithic device, semiconductor device or component, and microelectronic device or component, and similar expressions are often used interchangeably in this field. The present invention is applicable to all the above as they are generally understood in the field.

The term "gate" is context sensitive and can be used in two ways when describing integrated circuits. As used herein, gate refers to the insulated gate terminal, also referred to as a gate electrode, of a three terminal FET when used in the context of transistor circuit configuration, and refers to a circuit for realizing

an arbitrary logical function when used in the context of a logic gate. A FET can be viewed as a four terminal device when the semiconductor body is considered.

Polycrystalline silicon is a nonporous form of silicon made up of randomly oriented crystallites or domains. Polycrystalline silicon is often formed by
5 chemical vapor deposition from a silicon source gas or other methods and has a structure that contains large-angle grain boundaries, twin boundaries, or both. Polycrystalline silicon is often referred to in this field as polysilicon, or sometimes more simply as poly.

Source/drain terminals refer to the terminals of a FET, between which
10 conduction occurs under the influence of an electric field, subsequent to the inversion of the semiconductor surface under the influence of an electric field resulting from a voltage applied to the gate terminal. Source/drain terminals are typically formed in a semiconductor substrate and have a conductivity type (i.e., p-type or n-type) that is the opposite of the conductivity type of the substrate.
15 Sometimes, source/drain terminals are referred to as junctions. Generally, the source and drain terminals are fabricated such that they are geometrically symmetrical. Source/drain terminals may include extensions, sometimes referred to as tips, which are shallower than other portions of the source/drain terminals. The tips typically extend toward the channel region of a FET, from the
20 main portion of the source/drain terminal. With geometrically symmetrical source and drain terminals it is common to simply refer to these terminals as source/drain terminals, and this nomenclature is used herein. Designers often designate a particular source/drain terminal to be a "source" or a "drain" on the basis of the voltage to be applied to that terminal when the FET is operated in a
25 circuit.

Substrate, as used herein, refers to the physical object that is the basic workpiece that is transformed by various process operations into the desired microelectronic configuration. A substrate may also be referred to as a wafer. Wafers, may be made of semiconducting, non-semiconducting, or combinations
30 of semiconducting and non-semiconducting materials.

The term vertical, as used herein, means substantially perpendicular to the surface of a substrate.

A schematic cross-section of a conventional FET is shown in Fig. 1. More particularly, as shown in Fig. 1, a substrate **102** has a gate dielectric layer **111** disposed over the surface thereof, and a patterned gate electrode is formed over gate dielectric layer **104** wherein the gate electrode has a polysilicon portion **108** and a silicided portion **107**. As shown, sidewall spacers **110** are disposed along laterally opposed sidewalls of the gate electrode. In this example of a conventional FET, substrate **102** is a silicon wafer, and gate dielectric layer **104** is a silicon dioxide layer.

Structural Examples

Figs. 2-4 show several illustrations of transistor structures which embody the present invention.

Fig. 2 shows a schematic cross-section of a MOSFET **200** illustrating one embodiment of the present invention. MOSFET **200** includes a gate dielectric **211** disposed over a portion of wafer **102**. It can be seen that, unlike the conventional MOSFET of Fig. 1, gate dielectric **211** conforms to a recess in wafer **102**. The recess has a bottom portions and substantially vertical sidewalls. A gate electrode is formed over gate dielectric **211**, the gate electrode having a polysilicon portion **208** and a silicide portion **107**. Sidewall spacers **110**, typically silicon nitride, are disposed adjacent the gate electrode. Source/drain extensions **205** are disposed adjacent gate dielectric **211**, and deep source/drain regions **204** are disposed substantially wafer **102** in a self-aligned fashion with respect to spacers **110**. The spatial relationship between deep source/drain regions **204**, source/drain extensions **205** and the channel region underlying gate dielectric **211**, are important in providing the electrical advantages of the present invention. By providing transistor **200** with a recessed channel region, source/drain extensions **205** may be elevated with respect thereto. In turn, by elevating source/drain extensions **205**, they may be made thicker for reduced

electrical resistivity, while appearing to be scaled down in thickness relative to their relationship with the channel region. Also, the innermost portions of source/drain extensions **205**, i.e., the portions nearest to the channel region, have a portion of the gate electrode overlying them. This arrangement is also
5 believed to provide improvements in electrical performance.

Fig. 3 shows a schematic cross-section of a MOSFET **300** illustrating an alternative embodiment of the present invention. MOSFET **300** includes a gate dielectric **311** disposed over a portion of wafer **102**. It can be seen that, unlike the conventional MOSFET of Fig. 1, gate dielectric **311** conforms to a recess in
10 wafer **102**. The recess has a bottom portions and tapered sidewalls. Typically, these tapered sidewalls form an angle greater than 90° with respect to the bottom portion of the recess. A gate electrode is formed over gate dielectric **311**, the gate electrode having a polysilicon portion **308** and a silicide portion **107**. Sidewall spacers **110**, typically silicon nitride, are disposed adjacent the gate
15 electrode. Source/drain extensions **305** are disposed adjacent gate dielectric **311**, and deep source/drain regions **304** are disposed substantially wafer **102** in a self-aligned fashion with respect to spacers **110**. The spatial relationship between deep source/drain regions **304**, source/drain extensions **305** and the
20 channel region underlying gate dielectric **311**, are important in providing the electrical advantages of the present invention. By providing transistor **300** with a recessed channel region, source/drain extensions **305** may be elevated with respect thereto. In turn, by elevating source/drain extensions **305**, they may be made thicker for reduced electrical resistivity, while appearing to be scaled down in thickness relative to their relationship with the channel region.

25 Fig. 4 shows a schematic cross-section of a MOSFET **400** illustrating another alternative embodiment of the present invention. MOSFET **400** includes a gate dielectric **411** disposed over a portion of wafer **102**. It can be seen that, unlike the conventional MOSFET of Fig. 1, gate dielectric **411** conforms to a recess in the wafer **102**. The recess has a curvilinear surface. A gate electrode
30 is formed over gate dielectric **411**, the gate electrode having a polysilicon portion

408 and a silicide portion **107**. Sidewall spacers **110**, typically silicon nitride, are disposed adjacent the gate electrode. Source/drain extensions **405** are disposed adjacent gate dielectric **411**, and deep source/drain regions **404** are disposed substantially wafer **102** in a self-aligned fashion with respect to spacers **110**. The spatial relationship between deep source/drain regions **404**, source/drain extensions **405** and the channel region underlying gate dielectric **411**, are important in providing the electrical advantages of the present invention. By providing transistor **400** with a recessed channel region, source/drain extensions **405** may be elevated with respect thereto. In turn, by elevating source/drain extensions **405**, they may be made thicker for reduced electrical resistivity, while appearing to be scaled down in thickness relative to their relationship with the channel region.

Many variations are possible within the scope of the present invention. For example, gate dielectric layer **104** is typically a thin layer of oxidized silicon, but the thickness and chemical make-up of gate dielectric layer **104** may be varied within the scope of the invention. Similarly, it will be clear to those skilled in the art, that silicide layers **106**, **107** may be formed from various metals, including but not limited to, titanium, tungsten, nickel, cobalt, and molybdenum; and silicide layers **106**, **107** are not required to be of the same material or the same thickness. In further alternatives, transistors in accordance with the present invention may be formed without silicide layers, and may further be formed with metal gate electrodes rather than polysilicon gate electrodes. Sidewall spacers **110** are typically formed of silicon nitride, but other suitable materials may be substituted, and the sidewall spacers may be comprised of more than one layer of material. In still further alternatives, the transistor may be formed with silicon germanium source/drain terminals. The foregoing description of alternative materials and structures is for illustrative purposes only, and is not intended as an exhaustive list of alternatives. Those skilled in the art will undoubtedly recognize further variations within the scope of the invention.

Process Examples

Processes embodying the present invention include a damascene transistor flow coupled with a self-aligned channel recess etch. No special equipment, other than that typically used for producing MOS integrated circuits is required. In typical embodiments, channel implant operations are performed on a silicon wafer in a conventional manner, an etch stop layer, typically silicon dioxide, and a damascene layer, typically silicon nitride, are then formed over the wafer. The damascene layer is then patterned using a reverse tone polysilicon (i.e., gate electrode) mask. Alternatively the damascene layer is patterned using the conventional polysilicon mask with a negative photoresist. The patterning of the damascene layer results in openings being formed in areas where the gate electrodes are to be formed. Typically, the etch stop layer at the bottom of the damascene layer opening is removed, and a first spacer may then be formed along the sidewalls of the openings in the damascene layer. These first spacers define regions of the channel that will be recessed. Several alternative processes for recessing the channel are available. For example, in one embodiment an anisotropic etch (e.g., dry etch) of the exposed silicon is performed to recess the transistor channel region. In another embodiment, the exposed silicon is first oxidized, and the oxide is then etched, resulting in a recess with a tapered, rather than vertically abrupt, transition edge. In a further alternative embodiment, the channel recess etch is performed using an isotropic etch (e.g., wet etch) of the exposed silicon, which results in a curvilinear shape for the channel recess. IN relation to the recessed channel, the source/drain extension are elevated.

After the channel recess operation, a gate dielectric, typically an oxide of silicon, is formed over the surface of the channel recess. A material, such as, but not limited to, polysilicon, may then be deposited over the surface of the wafer. A planarization operation, typically chemical mechanical polishing using the damascene layer as an etch stop, is then performed. The damascene and underlying etch stop layers are then removed and source/drain extensions are

formed, typically by ion implantation. Spacers are then formed along laterally opposed sidewalls of the gate electrodes. These spacers are often referred to as sidewall spacers. Deep source/drain regions are then formed, aligned to the sidewall spacers, typically by ion implantation.

5 Further description of illustrative processes embodying the present invention are provided below in connection with Figs. 5-22.

A first process embodying the present invention is described in conjunction with Figs. 5-12. Referring to Fig. 5, a silicon wafer **102** has an etch stop layer **502** formed thereon. Etch stop layer **502** is typically, but not required
10 to be an oxide of silicon. Etch stop layer **502** may be formed by thermal oxidation of the surface of wafer **102**, or by well-known deposition processes. A layer **504**, referred to hereinafter as a damascene layer, is formed over etch stop layer **502**. Damascene layer **504** is typically a deposited layer of silicon nitride.

After deposition, damascene layer **504** is patterned, so as to form
15 openings therein. Patterning is typically performed with well-known photolithography processes. The openings in damascene layer **504** have substantially vertical sidewalls, but this is not a requirement of the present invention. These openings correspond to the locations of transistor gate electrodes which are to be formed in a later stage of the process. The openings
20 in damascene layer **504** expose portions of underlying etch stop layer **502**. The exposed portions of etch stop layer **502** is removed to expose the underlying silicon wafer **102**. Fig. 6 shows the structure of Fig. 5 after the patterning of layers **504** and **502**.

Referring to Fig. 7, the structure of Fig. 6 is shown after two sets of
25 spacers have been formed adjacent the vertical sidewalls of the openings in layers **504**, **502**. A first spacer **508** is formed immediately adjacent to the sidewalls of the openings and a second spacer **510** is formed adjacent first spacer **508**, as shown in Fig. 7. First spacer **508** is typically formed from silicon nitride which has been deposited by CVD and then subjected to an anisotropic

etch. Second spacer **510** is typically formed from silicon dioxide which has been deposited by CVD and then subjected to an anisotropic etch.

Fig. 8 shows the structure of Fig. 7 after a recess **512** is formed in wafer **102**. The recess in the wafer **102** is formed by an anisotropic etch process (e.g., dry etching of silicon). Recess **512** has a bottom portion **514** and substantially vertical sidewalls **516**.

Subsequent to formation of recess **512**, second spacer **510** is removed, the exposed silicon surface is oxidized to form a gate dielectric layer **511**, and polysilicon **518** is deposited over the surface of wafer **102** as shown in Fig. 9.

Those skilled in the art and having the benefit of this disclosure will recognize, that gate dielectric layer **511** may be formed in other ways or with other materials. The thickness and chemical composition of the gate dielectric may vary widely within the scope of the present invention.

Wafer **102** with polysilicon **518** over the surface thereof is planarized, typically by chemical mechanical polishing (CMP). The CMP operation uses damascene layer **504** as a polish stop. The results of the CMP operation, shown in Fig. 10, illustrate newly formed gate electrode **520**.

Fig. 11 shows the structure of Fig. 10 after the removal of damascene layer **504**, etch stop layer **502**, and first spacer **508**. More particularly, Fig. 11 shows polysilicon gate electrode **520** disposed superjacent gate dielectric **511**, which is formed over the surface of the recessed channel as shown in the figure.

Fig. 12 shows the structure of Fig. 11, after conventional semiconductor processing operations are used to implant source/drain extensions **524**, self-aligned to gate electrode **520**, form sidewall spacers **110**, implant deep source/drains **522**, and form silicide regions **106** and **107**.

An alternative embodiment is described in conjunction with Figs. 5-7 and 13-17. In this alternative illustrative embodiment, the processing operations as described above in connection with Figs. 5-7 are performed as before. However, referring to Fig. 13, rather than anisotropically etching the exposed silicon

surface, the exposed silicon surface is first oxidized, and then the oxidized silicon is removed, resulting in a recess **612** having a bottom portion **614** and tapered sidewalls **616**.

Fig. 14 shows the structure of Fig. 13, after the further processing operations of forming a gate dielectric layer **611** over a bottom portion **614** and tapered sidewalls **616** of recess **612**. Gate dielectric **611** is typically formed by oxidizing the exposed silicon surfaces of recess **612**. Those skilled in the art and having the benefit of this disclosure will recognize, that gate dielectric layer **611** may be formed in other ways or with other materials. The thickness and chemical composition of the gate dielectric may vary widely within the scope of the present invention.

Fig. 15 shows the structure of Fig. 14, after the further processing operations of forming individual gate electrodes **620** by removing the excess polysilicon. Gate electrode **620** is formed from polysilicon **618** by a CMP operation with damascene layer **504** acting as the polish stop layer. CMP of polysilicon is a well-known process operation in this field. Fig. 16 shows the structure of Fig. 15, after damascene layer **504**, etch stop layer **502**, and first spacer layer **508** are removed by etching. As can be seen, polysilicon gate electrode **620** is disposed superjacent gate dielectric **611**, which is formed over the surface of the recessed channel as shown in the figure.

Fig. 17 shows the structure of Fig. 16, after conventional semiconductor processing operations are used to implant source/drain extensions **624**, self-aligned to gate electrode **620**, form sidewall spacers **110**, implant deep source/drains **622**, and form silicide regions **106** and **107**.

A further alternative embodiment is described in conjunction with Figs. 5-7 and 18-22. In this alternative illustrative embodiment, the processing operations as described above in connection with Figs. 5-7 are performed as before. However, referring to Fig. 18, in this embodiment the exposed silicon surface is isotropically etched, resulting in a recess **712** having a curvilinear surface **714**.

Fig. 19 shows the structure of Fig. 18, after the further processing operations of forming a gate dielectric layer **711** over curvilinear surface **714** of recess **712**, the removal of second spacer **510** and the deposition of polysilicon layer **718**. Gate dielectric **711** is typically formed by oxidizing the exposed silicon surface of recess **712**. Those skilled in the art and having the benefit of this disclosure will recognize, that gate dielectric layer **711** may be formed in other ways or with other materials. The thickness and chemical composition of the gate dielectric may vary widely within the scope of the present invention.

Fig. 20 shows the structure of Fig. 19, after the further processing operations of forming individual gate electrodes **720** by removing the excess polysilicon. Gate electrode **720** is formed from polysilicon **718** by a CMP operation with damascene layer **504** acting as the polish stop layer. CMP of polysilicon is a well-known process operation in this field. Fig. 21 shows the structure of Fig. 20, after damascene layer **504**, etch stop layer **502**, and first spacer layer **508** are removed by etching. As can be seen, polysilicon gate electrode **720** is disposed superjacent gate dielectric **711**, which is formed over the surface of the recessed channel as shown in the figure.

Fig. 22 shows the structure of Fig. 21, after conventional semiconductor processing operations are used to implant source/drain extensions **705**, self-aligned to gate electrode **720**, form sidewall spacers **110**, implant deep source/drains **704**, and form silicide regions **106** and **107**.

In a further alternative, channel implants, typically performed prior to the formation of damascene layer **504**, are performed after damascene layer **504**, and etch stop layer **502** are patterned, and first and second spacers **508**, **510** are formed along the sidewalls of the openings in damascene layer **504**. As will be understood by those skilled in this field, by having the channel implant self-aligned to the transistor gate, junction capacitance is reduced, and, depending on the actual doping profiles of the channel implant, source/drain extension implant, and deep source/drain implant, counterdoping effects may also be reduced.

Fig. 23 is a flow diagram illustrating a process flow in accordance with the present invention. Openings are patterned, typically with conventional lithography techniques, in a damascene layer disposed on a wafer (block **2302**). Spacers are then formed along the sidewalls of the openings in the damascene layer (block **2304**). Typically a first spacer layer, such as an oxide of silicon, is formed and a second spacer layer, typically a nitride of silicon, is formed adjacent to the first spacer layer. A recess is then formed at the locations defined by the openings (block **2306**). The specific shape of the recesses may be varied within the scope of the present invention. For example, recesses may be shaped rectangularly, trapezoidally, curvilinearly, and so on. The various shapes may be achieved by applying corresponding various etch techniques. Isotropic and anisotropic etching are two examples. A gate dielectric is then formed over the recess (block **2308**) and a gate electrode is formed over the gate dielectric (block **2310**). Source/drain extensions are formed, typically by ion implantation, self-aligned to the gate electrode (block **2312**).

Conclusion

Embodiments of the present invention advantageously provide a field effect transistor structure having very short channel length and relatively low source/drain extension resistivity without the adverse short channel effects of conventional MOSFETs having equivalent channel lengths and source/drain extension resistivities. Embodiments of the present invention have source/drain extensions that are elevated relative the channel region of a MOSFET

A further advantage of particular embodiments of the present invention is reduced parasitic junction capacitance resulting from performing the channel implant only into portions of the wafer that will become the channel regions of transistors.

Those skilled in the art and having the benefit of this disclosure will recognize that although field oxide regions are not shown in the Figures, the operations and structures shown and described herein, are compatible with

various field oxide isolation architectures. Examples of field oxide isolation architectures include shallow trench isolation regions in a surface of a substrate, and the older local oxidation of silicon, which often formed non-planarized oxide isolation regions.

5. It will be understood by those skilled in the art having the benefit of this disclosure that many design choices are possible within the scope of the present invention. For example, structural parameters, including but not limited to, gate insulator thickness, gate insulator materials, gate electrode thickness, sidewall spacer material, inter-layer dielectric material, isolation trench depth, and S/D
- 10 and well doping concentrations may all be varied from that shown or described in connection with the illustrative embodiments.

- It will be understood that various other changes in the details, materials, and arrangements of the parts and steps which have been described and illustrated may be made by those skilled in the art having the benefit of this
- 15 disclosure without departing from the principles and scope of the invention as expressed in the subjoined Claims.